# MC10H124

# Quad TTL-to-MECL Translator With TTL Strobe Input

The MC10H124 is a quad translator for interfacing data and control signals between a saturated logic section and the MECL section of digital systems. The 10H part is a functional/pinout duplication of the standard MECL 10K family part, with 100% improvement in propagation delay, and no increase in power−supply current.

- Propagation Delay, 1.5 ns Typical
- Improved Noise Margin 150 mV
  (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K−Compatible
- Pb−Free Packages are Available*

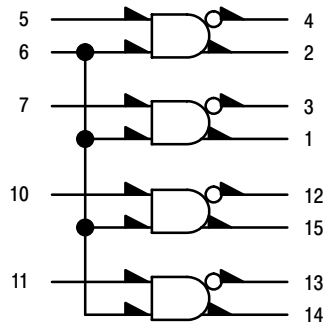
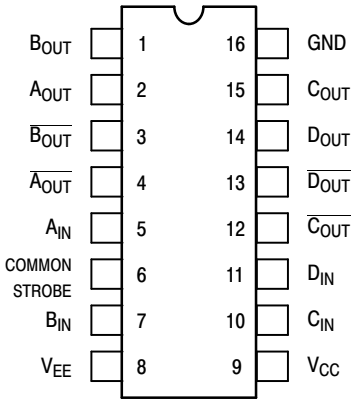



**Figure 1. Logic Diagram**




Pin assignment is for Dual−in−Line Package.
For PLCC pin assignment, see Table 1.

**Figure 2. Pin Assignment**

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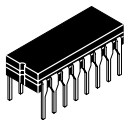
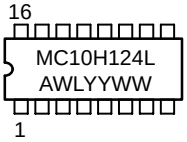
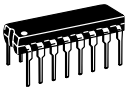
**MARKING DIAGRAMS**

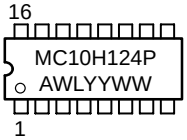


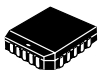
**CDIP−16**
**L SUFFIX**
**CASE 620A**



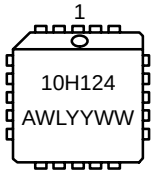



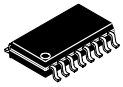
**PDIP−16**
**P SUFFIX**
**CASE 648**



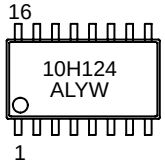



**PLCC−20**
**FN SUFFIX**
**CASE 775**



**EIAJ−16**
**M SUFFIX**
**CASE 966**




A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

**ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**Table 1. DIP CONVERSION TABLE**

**16−Pin DIL to 20−Pin PLCC**

| | | | | | | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 16 PIN DIL | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 |
| 20 PIN PLCC | 2 | 3 | 4 | 5 | 7 | 8 | 9 | 10 | 12 | 13 | 14 | 15 | 17 | 18 | 19 | 20 |

**Table 2. MAXIMUM RATINGS**

| Symbol | Characteristic | Rating | Unit |
|---|---|---|---|
| $V_{EE}$ | Power Supply ($V_{CC}$ = 5.0 V) | −8.0 to 0 | Vdc |
| $V_{CC}$ | Power Supply ($V_{EE}$ = −5.2 V) | 0 to +7.0 | Vdc |
| $V_I$ | Input Voltage ($V_{CC}$ = 5.0 V) TTL | 0 to $V_{CC}$ | Vdc |
| $I_{out}$ | Output Current − Continuous<br>− Surge | 50<br>100 | mA |
| $T_A$ | Operating Temperature Range | 0 to +75 | °C |
| $T_{stg}$ | Storage Temperature Range − Plastic<br>− Ceramic | −55 to +150<br>−55 to +165 | °C |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

**Table 3. ELECTRICAL CHARACTERISTICS** ($V_{EE}$ = −5.2 V ±5%, $V_{CC}$ = 5.0 V ± 5.0%)

| | | 0° | | 25° | | 75° | | |
|---|---|---|---|---|---|---|---|---|
| Symbol | Characteristic | Min | Max | Min | Max | Min | Max | Unit |
| $I_E$ | Negative Power Supply Drain Current | − | 72 | − | 66 | − | 72 | mA |
| $I_{CCH}$<br>$I_{CCL}$ | Positive Power Supply Drain Current | −<br>− | 16<br>25 | −<br>− | 16<br>25 | −<br>− | 18<br>25 | mA |
| $I_R$ | Reverse Current<br>Pin 6<br>Pin 7 | <br>−<br>− | <br>200<br>50 | <br>−<br>− | <br>200<br>50 | <br>−<br>− | <br>200<br>50 | μA |
| $I_F$ | Forward Current<br>Pin 6<br>Pin 7 | <br>−<br>− | <br>−12.8<br>−3.2 | <br>−<br>− | <br>−12.8<br>−3.2 | <br>−<br>− | <br>−12.8<br>−3.2 | mA |
| $V_{(BR)in}$ | Input Breakdown Voltage | 5.5 | − | 5.5 | − | 5.5 | − | Vdc |
| $V_I$ | Input Clamp Voltage | − | −1.5 | − | −1.5 | − | −1.5 | Vdc |
| $V_{OH}$ | High Output Voltage | −1.02 | −0.84 | −0.98 | −0.81 | −0.92 | −0.735 | Vdc |
| $V_{OL}$ | Low Output Voltage | −1.95 | −1.63 | −1.95 | −1.63 | −1.95 | −1.60 | Vdc |
| $V_{IH}$ | High Input Voltage | 2.0 | − | 2.0 | − | 2.0 | − | Vdc |
| $V_{IL}$ | Low Input Voltage | − | 0.8 | − | 0.8 | − | 0.8 | Vdc |

1. Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50 Ω resistor to −2.0 V.

**Table 4. AC CHARACTERISTICS**

| | | 0° | | 25° | | 75° | | |
|---|---|---|---|---|---|---|---|---|
| Symbol | Characteristic | Min | Max | Min | Max | Min | Max | Unit |
| $t_{pd}$ | Propagation Delay | 0.55 | 2.5 | 0.55 | 2.65 | 0.85 | 3.1 | ns |
| $t_r$ | Rise Time | 0.5 | 1.5 | 0.5 | 1.6 | 0.5 | 1.7 | ns |
| $t_f$ | Fall Time | 0.5 | 1.5 | 0.5 | 1.6 | 0.5 | 1.7 | ns |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

## APPLICATIONS INFORMATION

The MC10H124 has TTL−compatible inputs and MECL complementary open−emitter outputs that allow use as an inverting/non−inverting translator or as a differential line driver. When the common strobe input is at the low−logic level, it forces all true outputs to a MECL low−logic state and all inverting outputs to a MECL high−logic state.

An advantage of this device is that TTL−level information can be transmitted differentially, via balanced twisted pair lines, to MECL equipment, where the signal can be received by the MC10H115 or MC10H116 differential line receivers. The power supply requirements are ground, +5.0 V, and −5.2 V.

### ORDERING INFORMATION

| Device | Package | Shipping† |
|---|---|---|
| MC10H124L | CDIP−16 | 25 Units/Rail |
| MC10H124P | PDIP−16 | 25 Units/Rail |
| MC10H124PG | PDIP−16 (Pb−Free) | 25 Units/Rail |
| MC10H124FN | PLCC−20 | 46 Units/Rail |
| MC10H124FNG | PLCC−20 (Pb−Free) | 46 Units/Rail |
| MC10H124FNR2 | PLCC−20 | 1000 Tape & Reel |
| MC10H124M* | EIAJ−16 (Pb−Free) | 50 Units/Rail |
| MC10H124MEL* | EIAJ−16 (Pb−Free) | 2000 Tape & Reel |

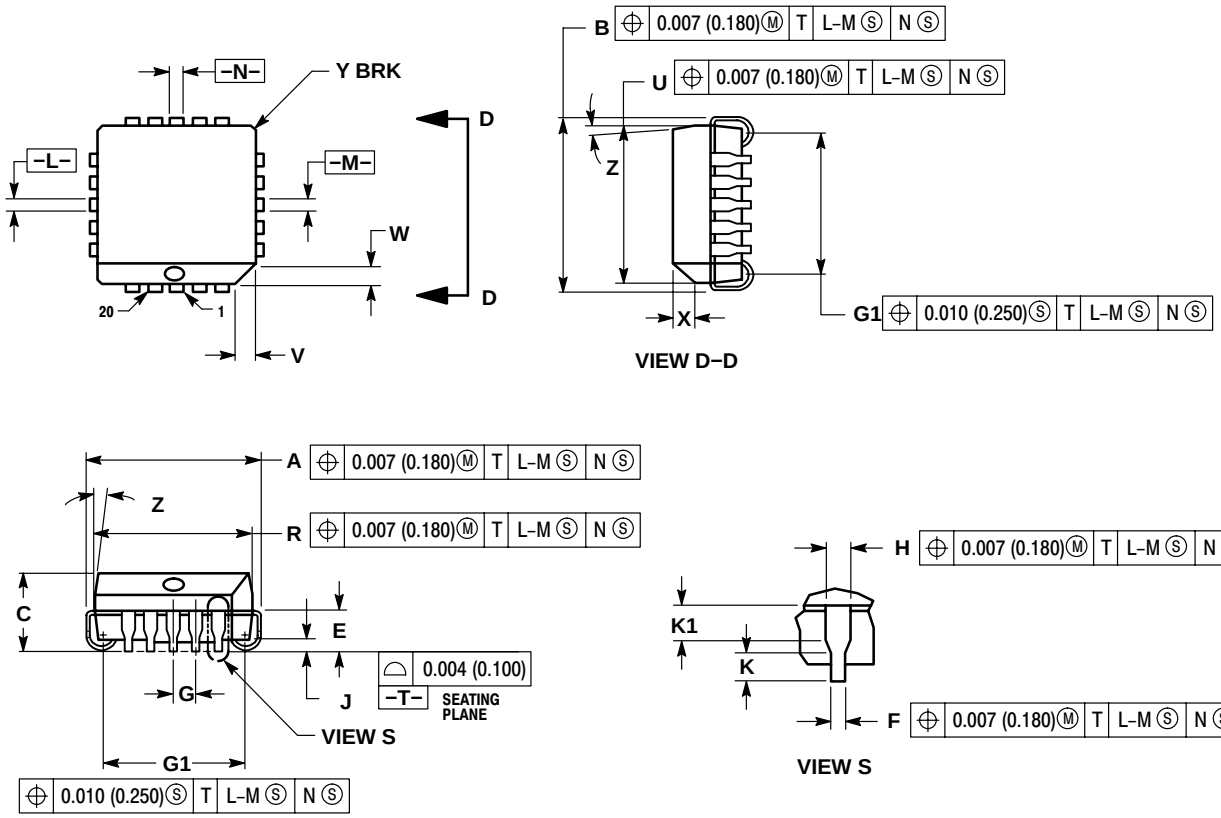
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This device is manufactured with a Pb−Free external lead finish only.

### Resource Reference of Application Notes

**AN1405/D** − ECL Clock Distribution Techniques
**AN1406/D** − Designing with PECL (ECL at +5.0 V)
**AN1503/D** − ECLinPS™ I/O SPiCE Modeling Kit
**AN1504/D** − Metastability and the ECLinPS Family
**AN1568/D** − Interfacing Between LVDS and ECL
**AN1642/D** − The ECL Translator Guide
**AND8001/D** − Odd Number Counters Design
**AND8002/D** − Marking and Date Codes
**AND8020/D** − Termination of ECL Logic Devices
**AND8066/D** − Interfacing with ECLinPS
**AND8090/D** − AC Characteristics of ECL Devices

## PACKAGE DIMENSIONS

**PLCC−20**
**FN SUFFIX**
PLASTIC PLCC PACKAGE
CASE 775−02
ISSUE D

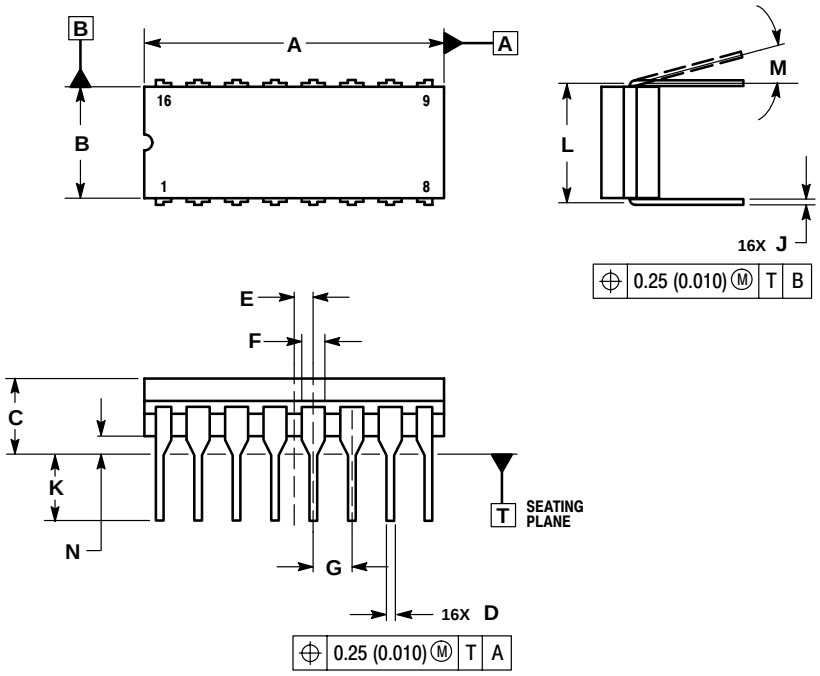



NOTES:
1. DATUMS −L−, −M−, AND −N− DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM −T−, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

| | INCHES | | MILLIMETERS | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | 0.385 | 0.395 | 9.78 | 10.03 |
| B | 0.385 | 0.395 | 9.78 | 10.03 |
| C | 0.165 | 0.180 | 4.20 | 4.57 |
| E | 0.090 | 0.110 | 2.29 | 2.79 |
| F | 0.013 | 0.019 | 0.33 | 0.48 |
| G | 0.050 BSC | | 1.27 BSC | |
| H | 0.026 | 0.032 | 0.66 | 0.81 |
| J | 0.020 | --- | 0.51 | --- |
| K | 0.025 | --- | 0.64 | --- |
| R | 0.350 | 0.356 | 8.89 | 9.04 |
| U | 0.350 | 0.356 | 8.89 | 9.04 |
| V | 0.042 | 0.048 | 1.07 | 1.21 |
| W | 0.042 | 0.048 | 1.07 | 1.21 |
| X | 0.042 | 0.056 | 1.07 | 1.42 |
| Y | --- | 0.020 | --- | 0.50 |
| Z | 2° | 10° | 2° | 10° |
| G1 | 0.310 | 0.330 | 7.88 | 8.38 |
| K1 | 0.040 | --- | 1.02 | --- |

## PACKAGE DIMENSIONS

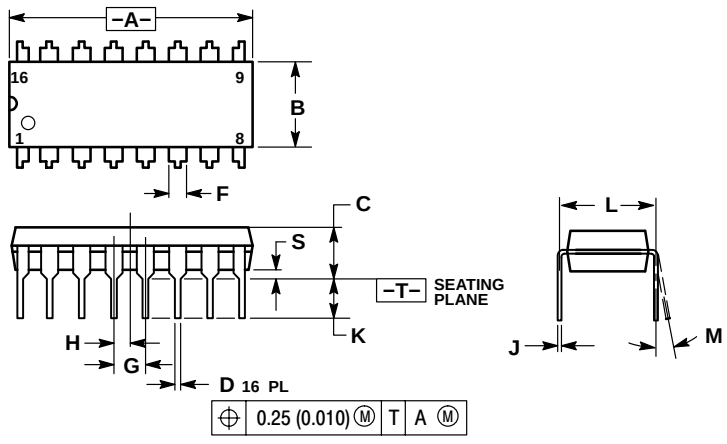
**CDIP−16**
**L SUFFIX**
CERAMIC DIP PACKAGE
CASE 620A−01
ISSUE O




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.
5 THIS DRAWING REPLACES OBSOLETE CASE OUTLINE 620−10.

| | INCHES | | MILLIMETERS | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | 0.750 | 0.785 | 19.05 | 19.93 |
| B | 0.240 | 0.295 | 6.10 | 7.49 |
| C | --- | 0.200 | --- | 5.08 |
| D | 0.015 | 0.020 | 0.39 | 0.50 |
| E | 0.050 BSC | | 1.27 BSC | |
| F | 0.055 | 0.065 | 1.40 | 1.65 |
| G | 0.100 BSC | | 2.54 BSC | |
| H | 0.008 | 0.015 | 0.21 | 0.38 |
| K | 0.125 | 0.170 | 3.18 | 4.31 |
| L | 0.300 BSC | | 7.62 BSC | |
| M | 0 ° | 15 ° | 0 ° | 15 ° |
| N | 0.020 | 0.040 | 0.51 | 1.01 |

**PDIP−16**
**P SUFFIX**
PLASTIC DIP PACKAGE
CASE 648−08
ISSUE T

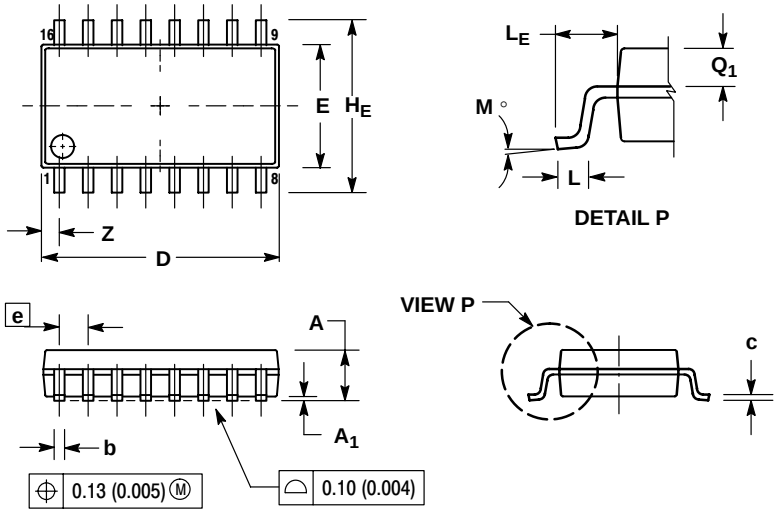



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

| | INCHES | | MILLIMETERS | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | 0.740 | 0.770 | 18.80 | 19.55 |
| B | 0.250 | 0.270 | 6.35 | 6.85 |
| C | 0.145 | 0.175 | 3.69 | 4.44 |
| D | 0.015 | 0.021 | 0.39 | 0.53 |
| F | 0.040 | 0.70 | 1.02 | 1.77 |
| G | 0.100 BSC | | 2.54 BSC | |
| H | 0.050 BSC | | 1.27 BSC | |
| J | 0.008 | 0.015 | 0.21 | 0.38 |
| K | 0.110 | 0.130 | 2.80 | 3.30 |
| L | 0.295 | 0.305 | 7.50 | 7.74 |
| M | 0 ° | 10 ° | 0 ° | 10 ° |
| S | 0.020 | 0.040 | 0.51 | 1.01 |

## PACKAGE DIMENSIONS

**EIAJ−16**
**M SUFFIX**
16 PIN PLASTIC EIAJ PACKAGE
CASE 966−01
ISSUE O




NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 ( 0.018).

| | MILLIMETERS | | INCHES | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | --- | 2.05 | --- | 0.081 |
| $A_1$ | 0.05 | 0.20 | 0.002 | 0.008 |
| b | 0.35 | 0.50 | 0.014 | 0.020 |
| c | 0.18 | 0.27 | 0.007 | 0.011 |
| D | 9.90 | 10.50 | 0.390 | 0.413 |
| E | 5.10 | 5.45 | 0.201 | 0.215 |
| e | 1.27 BSC | | 0.050 BSC | |
| $H_E$ | 7.40 | 8.20 | 0.291 | 0.323 |
| L | 0.50 | 0.85 | 0.020 | 0.033 |
| $L_E$ | 1.10 | 1.50 | 0.043 | 0.059 |
| M | 0 ° | 10 ° | 0 ° | 10 ° |
| $Q_1$ | 0.70 | 0.90 | 0.028 | 0.035 |
| Z | --- | 0.78 | --- | 0.031 |



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**MC10H124/D**